

Global Optoelectronic Die Bonding Equipment Supply, Demand and Key Producers, 2026-2032

<https://marketpublishers.com/r/GE3EEBB9FAEBEN.html>

Date: July 2026

Pages: 150

Price: US\$ 4,480.00 (Single User License)

ID: GE3EEBB9FAEBEN

Abstracts

The global Optoelectronic Die Bonding Equipment market size is expected to reach \$ 365 million by 2032, rising at a market growth of 8.3% CAGR during the forecast period (2026-2032).

Optoelectronic Die Bonding Equipment refers to specialized packaging equipment used to place and bond laser diodes, VCSELs, photodiodes, avalanche photodiodes, detector arrays, emitter dies, receiver dies, microlenses, filters, or other optoelectronic functional chips onto ceramic carriers, metal heat sinks, TO headers, optical module substrates, sensor packages, or optoelectronic assemblies. These systems typically consist of a high-precision motion platform, machine-vision system, die pick-up mechanism, dispensing or stamping module, eutectic or soft-solder bonding module, thermocompression mechanism, heating stage, force-control system, and automated loading unit. Key requirements include 1-5 micron placement accuracy, thermal-management capability, low-void soldering, batch consistency, and stable handling of small and fragile dies. Major production regions include the United States, Germany, Sweden, Singapore, Japan, China, South Korea, and Taiwan, with applications covering optical communication modules, active optical cables, data-center optical devices, automotive LiDAR, 3D sensing, industrial sensing, medical optoelectronic devices, and high-power laser assemblies.

In 2025, global production of optoelectronic die bonding equipment reached approximately 230-270 units, with mainstream FOB prices of about 0.45-1.10 million USD per unit. Lower-end configurations were mainly used for semi-automatic optoelectronic device placement, R&D validation, and small-to-medium-volume module packaging, while high-end configurations integrated high-speed automated pick-and-place, eutectic bonding, low-void soldering, vision alignment, heating and force control,

automated loading, and multi-die sequential placement capabilities, serving volume manufacturing of optical modules, laser diodes, VCSELs, photodetectors, LiDAR, high-power laser devices, and sensors.

The global Optoelectronic Die Bonding Equipment market is benefiting from the expansion of high-speed optical communications, AI data centers, automotive sensing, industrial sensing, and high-power laser applications. The market is upgrading from traditional small-batch precision assembly toward manufacturing models with higher speed, stronger consistency, and greater automation. Optical modules and active optical cables require high-volume and highly consistent placement of laser dies, photodetectors, and lenses; VCSEL and 3D sensing applications emphasize array assembly, yield, and cost control; while LiDAR and high-power laser devices place greater weight on thermal management, soldering reliability, and long-term stability. Compared with Photonics Die Bonding Equipment, Optoelectronic Die Bonding Equipment has a more mature application base, a broader customer group, and a higher share of production equipment, with demand closely linked to optical module capacity expansion, laser-device packaging capacity, and sensor industry cycles.

The main challenges include equipment price competition, fragmented customer processes, diverse package formats, and cyclical downstream demand. Some optoelectronic devices require lower placement accuracy than silicon photonics and CPO applications, but they place higher requirements on throughput, solder void rate, thermal resistance, batch stability, and equipment uptime. Equipment suppliers therefore need to balance precision and productivity. As 800G, 1.6T, VCSEL arrays, automotive LiDAR, industrial vision, and medical optoelectronic applications continue to develop, Optoelectronic Die Bonding Equipment will gradually evolve from standalone die attach systems into automated production-line modules. Future competition will focus on high UPH, low failure rate, multi-die compatibility, rapid changeover, process traceability, and integration with inspection equipment.

This report studies the global Optoelectronic Die Bonding Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Optoelectronic Die Bonding Equipment and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Optoelectronic Die Bonding Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Optoelectronic Die Bonding Equipment total production and demand, 2021-2032, (Units)

Global Optoelectronic Die Bonding Equipment total production value, 2021-2032, (USD Million)

Global Optoelectronic Die Bonding Equipment production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Units), (based on production site)

Global Optoelectronic Die Bonding Equipment consumption by region & country, CAGR, 2021-2032 & (Units)

U.S. VS China: Optoelectronic Die Bonding Equipment domestic production, consumption, key domestic manufacturers and share

Global Optoelectronic Die Bonding Equipment production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Units)

Global Optoelectronic Die Bonding Equipment production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Units)

Global Optoelectronic Die Bonding Equipment production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Units)

This report profiles key players in the global Optoelectronic Die Bonding Equipment market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Mycronic AB, ASMPT Ltd., ficonTEC Service GmbH, Palomar Technologies, Inc., Finetech GmbH & Co. KG, SET Corporation, TRESKY GmbH, BE Semiconductor Industries N.V., EV Group, Shibuya Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Optoelectronic Die Bonding Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Units) and average price (US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the

forecast year.

Global Optoelectronic Die Bonding Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Optoelectronic Die Bonding Equipment Market, Segmentation by Type:

Chip to Submount Die Bonders

Chip on Carrier Die Bonders

Optical Module Die Bonders

Others

Global Optoelectronic Die Bonding Equipment Market, Segmentation by Equipment Form:

Fully Automated Inline Systems

Standalone Automatic Systems

Semi Automatic Systems

Others

Global Optoelectronic Die Bonding Equipment Market, Segmentation by Bonding Process:

Epoxy Die Attach

Eutectic Solder Bonding

Soft Solder Bonding

Others

Global Optoelectronic Die Bonding Equipment Market, Segmentation by Downstream Industry:

Data Communications and Telecom

Automotive Sensing

Industrial and Medical Optoelectronics

Others

Global Optoelectronic Die Bonding Equipment Market, Segmentation by Application:

Laser Diode Devices

VCSEL Devices

Photodetector Devices

Others

Companies Profiled:

Mycronic AB

ASMPT Ltd.

ficonTEC Service GmbH

Palomar Technologies, Inc.

Finetech GmbH & Co. KG

SET Corporation

TRESKY GmbH

BE Semiconductor Industries N.V.

EV Group

Shibuya Corporation

Toray Engineering Co., Ltd.

Hanwha Semitech Co., Ltd.

Microview Intelligent Packaging Technology (Shenzhen) Co., Ltd.

Bozhon Precision Industry Technology Co., Ltd.

SHENZHEN AIT PRECISION TECHNOLOGY CO., LTD.

Suzhou Lieqi Intelligent Equipment Co., Ltd.

Dongguan Precision Intelligent Technology Co., Ltd.

DongGuan Attach Point Intelligent Equipment Co., Ltd.

Your-Chance Technology Co. Ltd.

Key Questions Answered:

1. How big is the global Optoelectronic Die Bonding Equipment market?
2. What is the demand of the global Optoelectronic Die Bonding Equipment market?
3. What is the year over year growth of the global Optoelectronic Die Bonding Equipment market?
4. What is the production and production value of the global Optoelectronic Die Bonding Equipment market?
5. Who are the key producers in the global Optoelectronic Die Bonding Equipment market?
6. What are the growth factors driving the market demand?

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